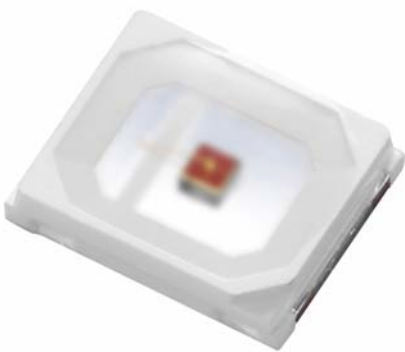


## SMD ■ Middle Power LED

### 67-21S/NY2C-D8595B7L32128Z6/2T



#### Features

- PLCC-2 package
- Top view Yellow LED
- Wide viewing angle
- Pb-free
- RoHS compliant
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br<900ppm,Cl<900ppm,Br+Cl<1500ppm)

#### Description

The Everlight 67-21S package has high efficacy, Middle Power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for all lighting applications.

#### Applications

- Decorative and Entertainment Lighting
- Agriculture Lighting
- General use

## Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Yellow	Water Clear

## Absolute Maximum Ratings (T<sub>Soldering</sub>=25°C)

Parameter	Symbol	Rating	Unit
Forward Current	I <sub>F</sub>	70	mA
Peak Forward Current (Duty 1/10 @10ms)	I <sub>FP</sub>	140	mA
Power Dissipation	P <sub>d</sub>	196	mW
Electrostatic Discharge(HBM)	ESD	2000	V
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +100	°C
Thermal Resistance (Junction / Soldering point)	R <sub>th J-S</sub>	21	°C/W
Junction Temperature	T <sub>j</sub>	115	°C
Soldering Temperature	T <sub>sol</sub>	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

Note:

The products are sensitive to static electricity and must be carefully taken when handling products

## Electro-Optical Characteristics (T<sub>Soldering</sub>=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous flux	I <sub>v</sub>	8.5	-----	13.0	lm	I <sub>F</sub> =60mA
Forward Voltage	V <sub>F</sub>	2.1	-----	2.8	V	I <sub>F</sub> =60mA
Viewing Angle	2θ <sub>1/2</sub>	-----	120	-----	deg	I <sub>F</sub> =60mA
Reverse Current	I <sub>R</sub>	-----	-----	10	μA	V <sub>R</sub> =5V

Notes:

1. Tolerance of Luminous flux : ±11%.
2. Tolerance of Forward Voltage: ±0.1V.

### Bin Range of Luminous flux

Bin Code	Min.	Max.	Unit	Condition
B7	8.5	9.0	lm	I <sub>F</sub> =60mA
B8	9.0	9.5		
B9	9.5	10.0		
L1	10.0	11.0		
L2	11.0	12.0		
L3	12.0	13.0		

Notes:  
 Tolerance of Luminous flux: ±11%

### Bin Range of Forward Voltage

Bin Code	Min.	Max.	Unit	Condition
28	2.1	2.2	V	I <sub>F</sub> =60mA
29	2.2	2.3		
30	2.3	2.4		
31	2.4	2.5		
32	2.5	2.6		
33	2.6	2.7		
34	2.7	2.8		

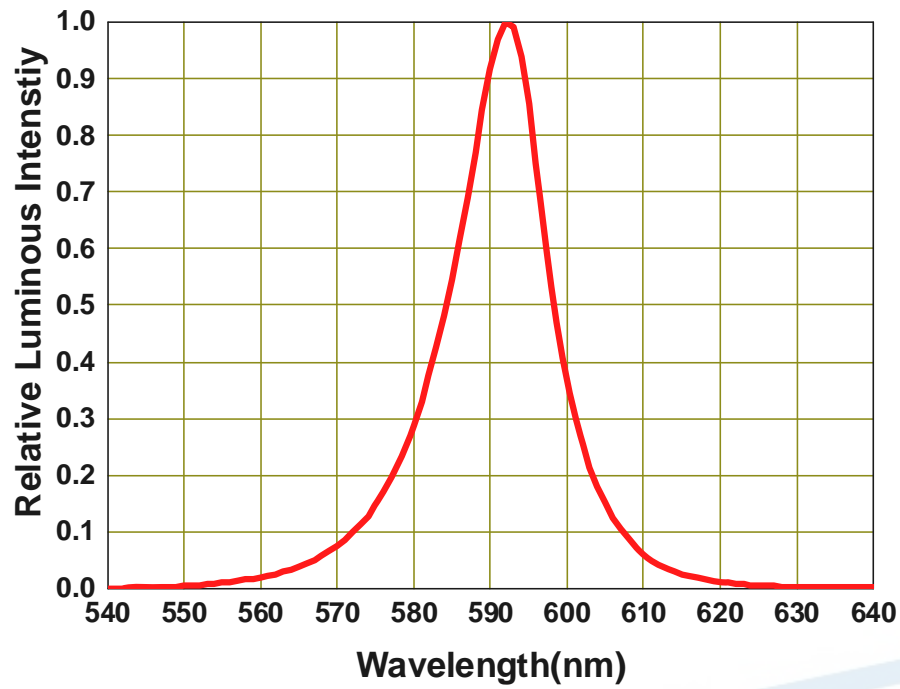
Note:  
 Tolerance of Forward Voltage: ±0.1V.

### Dominant Wavelength Bins

Bin Code	Min.	Max.	Unit	Condition
Y52	585	590	nm	I <sub>F</sub> =60mA
Y53	590	595		

Notes:  
 Dominant / Peak wavelength measurement tolerance: ±1nm.

## Spectrum Distribution



## Typical Electro-Optical Characteristics Curves

Fig.1 – Forward Voltage Shift vs. Junction Temperature

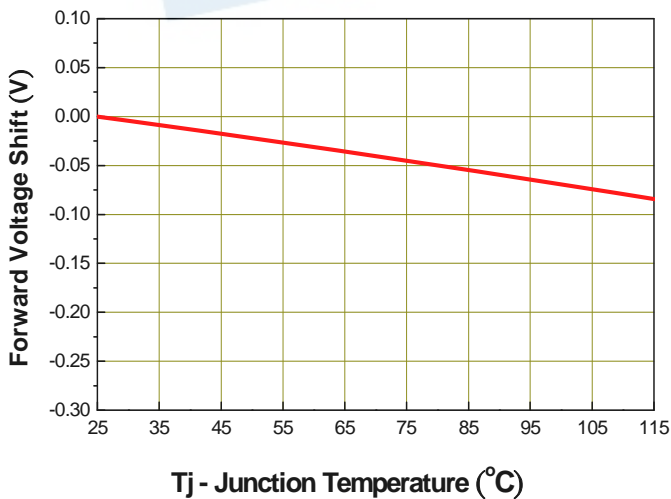
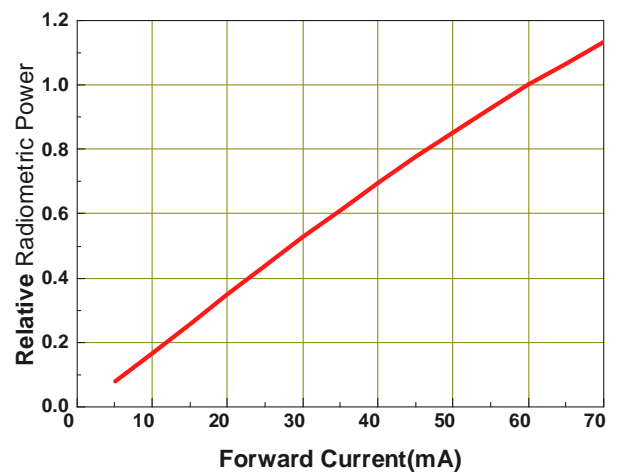


Fig.2 - Relative Radiometric Power vs. Forward Current



Typical Electro-Optical Characteristics Curves

Fig.3 - Relative Luminous Intensity vs. Junction Temperature

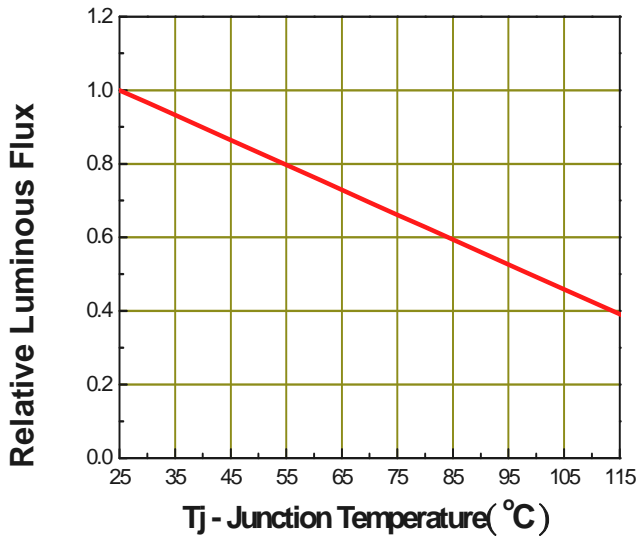


Fig.4 - Forward Current vs. Forward Voltage

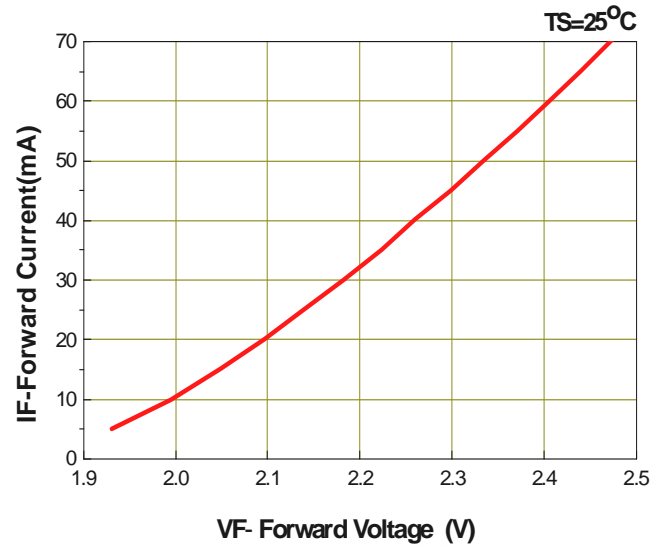


Fig.5 – Max. Driving Forward Current vs. Soldering Temperature

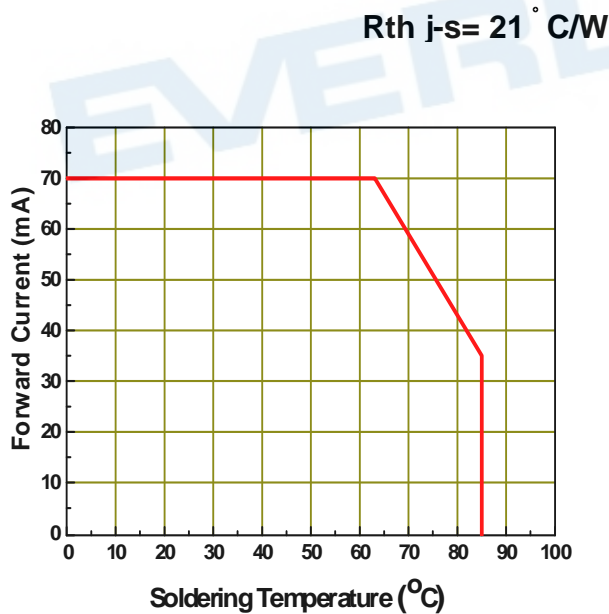
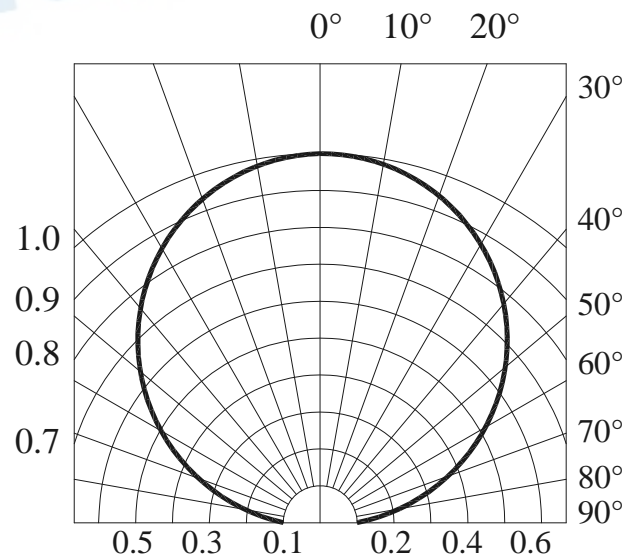
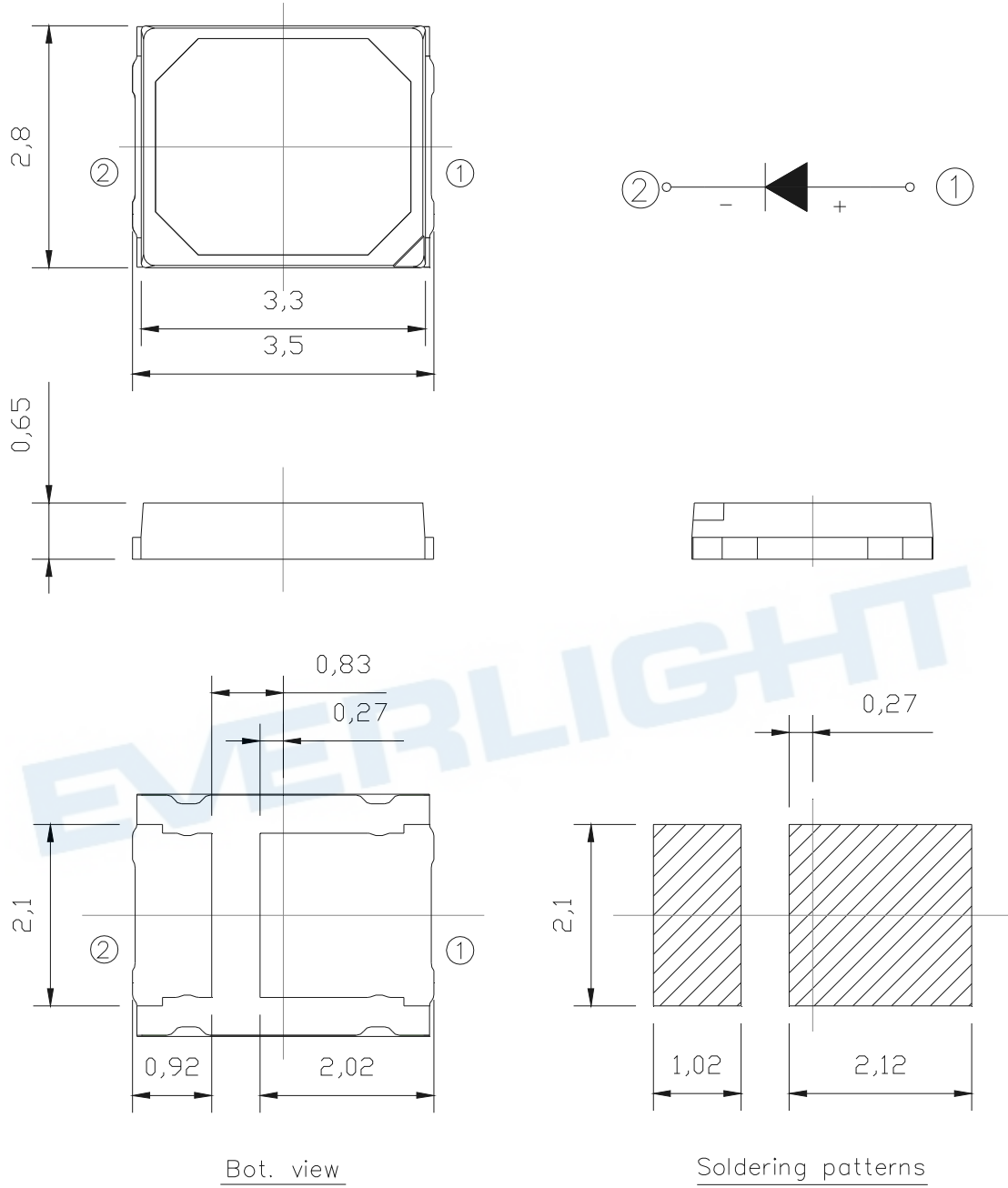


Fig.6 – Radiation Diagram



Package Dimension

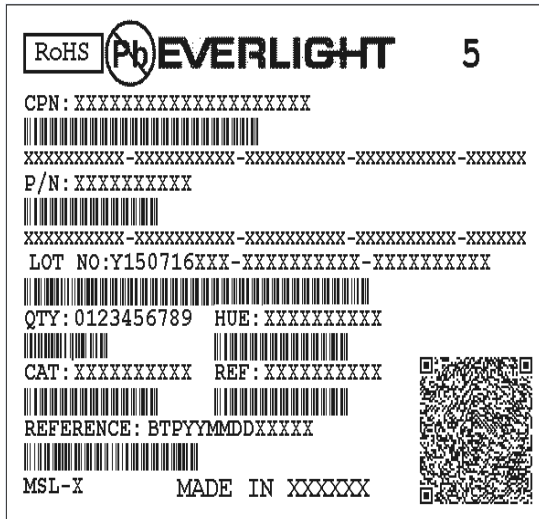


Suggested pad dimension is just reference only.  
 Please modify the pad dimension based on individual need.

Note:  
 Tolerance unless mentioned is  $\pm 0.15$  mm; Unit = mm

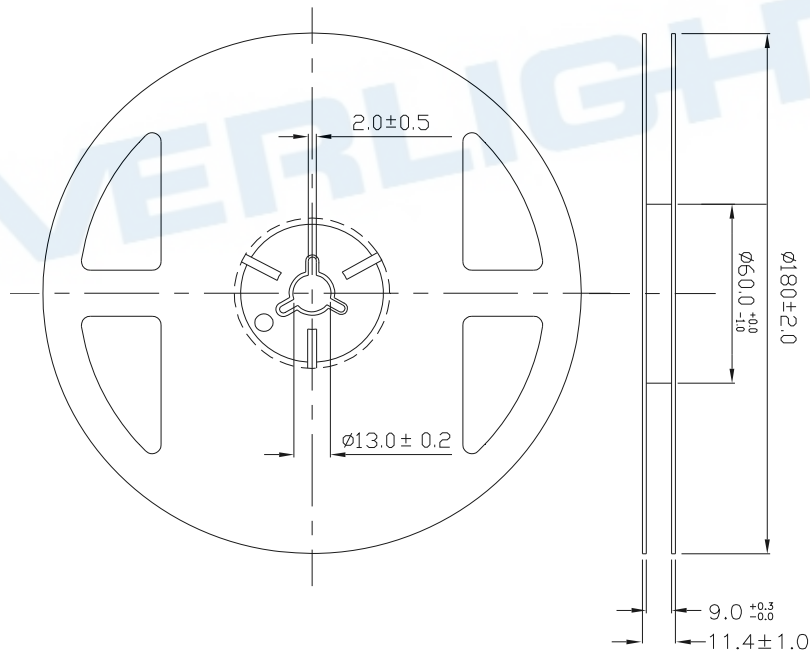
Moisture Resistant Packing Materials

Label Explanation



- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

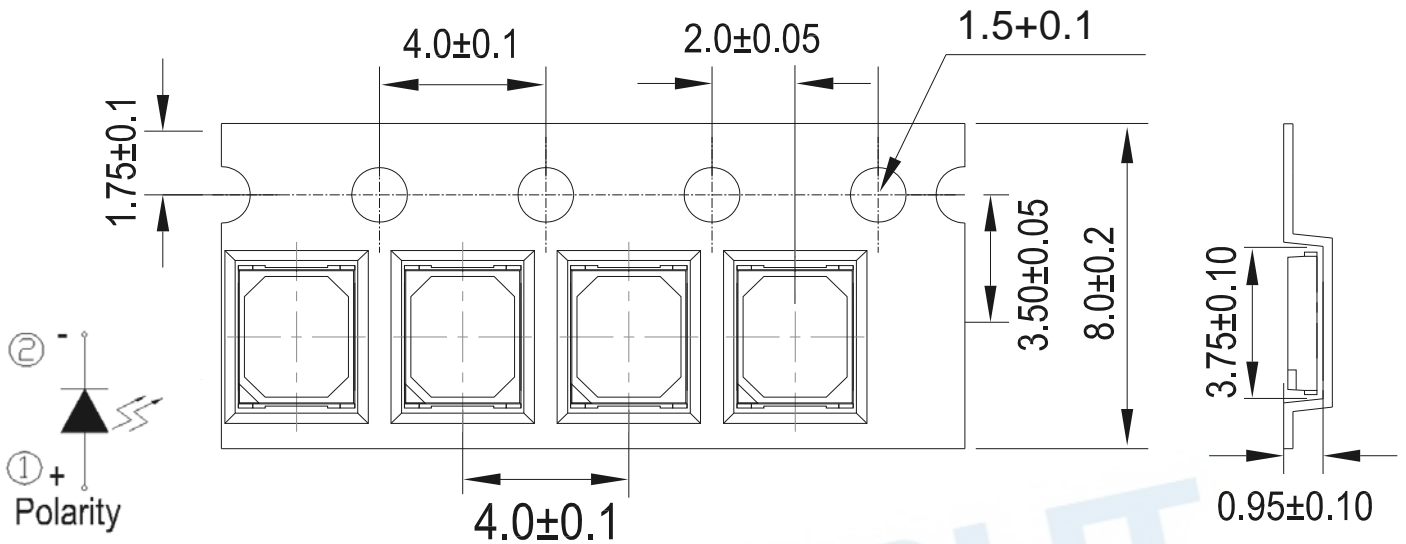
Reel Dimensions



Note:  
 Tolerances unless mentioned  $\pm 0.1$ mm. Unit = mm

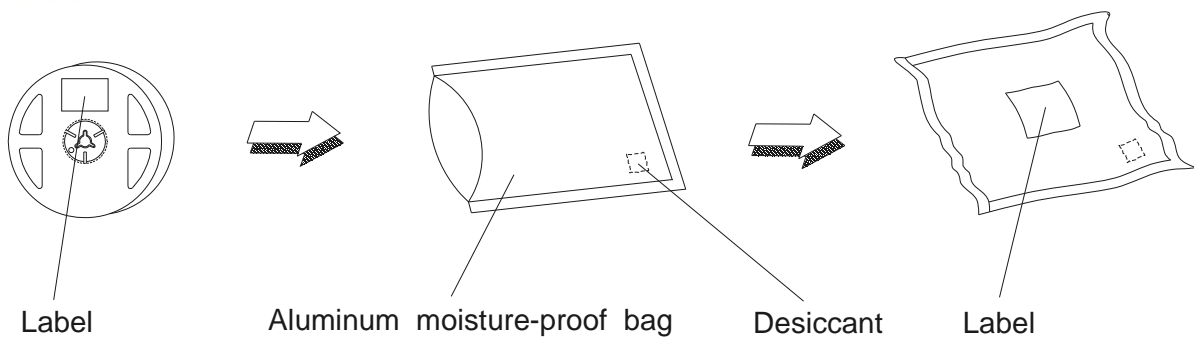
Carrier Tape Dimensions: Loaded Quantity 250/500/1000/2000/3000/4000 pcs. Per Reel

Progressive direction



Note:  
 Tolerance unless mentioned is ±0.1mm; Unit = mm

Moisture Resistant Packing Process





## Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

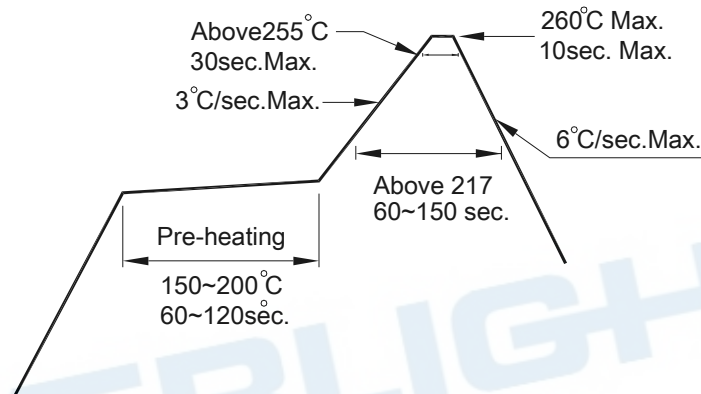
Confidence level : 90%

LTPD : 10%

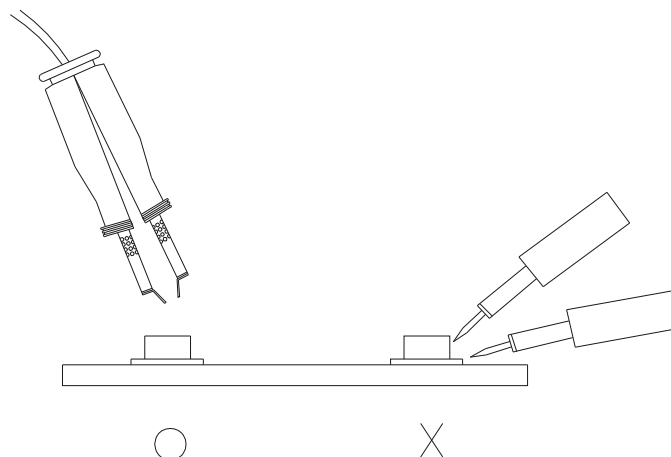
No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Resistance to Solder Heat	Temp. : 260°C/10sec.	3 Times.	8 PCS.	0/1
2	Temperature Cycle	-40°C~100°C / Dwell time 30min	200 Cycles	8 PCS.	0/1
3	High Temperature/Humidity Life	Ta=85°C,85%RH, I <sub>F</sub> = 35 mA	1000 Hrs.	8 PCS.	0/1
4	Low Temperature Life	Ta=-40°C, I <sub>F</sub> = 70mA	1000 Hrs.	8 PCS.	0/1
5	High Temperature Life	Ta=60°C, I <sub>F</sub> =70mA	3000 Hrs.	8 PCS.	0/1
6	High Temperature Life	Ta=85°C, I <sub>F</sub> =35mA	3000 Hrs.	8 PCS.	0/1
7	Pulse	ON 30ms / OFF 2500ms	30000 CYCLES	8 PCS.	0/1
8	Thermal Shock	H : +100°C 20min ∩ 10 sec L : -40°C 20min	200 Cycles	8 PCS.	0/1
9	Power Temperature Cycle	H : +100°C 15min ∩ 5 min L : -40°C 15min I <sub>F</sub> =47 mA	200 Cycles	8 PCS.	0/1

## Precautions for Use

1. Over-current-proof  
Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).
2. Storage
  - 2.1 Do not open moisture proof bag before the products are ready to use.
  - 2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.
  - 2.3 After opening the package: The LED's floor life is 168 Hrs under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
  - 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.  
Baking treatment: 60±5°C for 24 hours.
3. Soldering Condition
  - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.
4. Soldering Iron  
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.
5. Repairing  
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



## DISCLAIMER

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2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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